



FOCUS

Wafer Inspection System for Frame & Whole Wafer



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STI's **iFocus** is a highly intelligent precision wafer inspection system that offers a comprehensive solution for the inspection of frame and/or whole wafer.

Using STI's proprietary On-The-Fly (OTF™) vision, the **iFocus** can be configured to detect any type of micro defects arising from wafer processing, post dicing or packing.

The OTF™ optical system encompasses pioneering technology in areas such as optics and illumination design, 2D, 3D and active die inspection algorithms. Patented Simultaneous Dual Illumination Image Capture Technology is used to eliminate escape and reduce overkill without compromising throughput.

iFocus Specifications

INSPECTION	FRAME WAFER	WHOLE WAFER	FRAME/WHOLE WAFER
2D OTF™ SYSTEM	SYSTEM 100	SYSTEM 300	SYSTEM 500
3D OTF™ SYSTEM	SYSTEM 150	SYSTEM 350	SYSTEM 550

SPECIFICATIONS	DESCRIPTION
Wafer Type	Frame Whole
Wafer Size (in.)	6, 8, 12 (Frame) 6, 8, 12 (Whole)
Wafer Thickness	0.40 mm to 1.20 mm
Material Handling	Standard cassette 6", 8" or 12" cassette (frame) 6" or 8" open cassette (whole)
Load Port	SEMI compliant FOUP Autodoor FOSB 300 mm whole wafer 8" open cassette adaptor (optional)
UPH	2D OTF™ : 30 WPH @2.5x magnification 3D OTF™ : 10 WPH (Based on 200 mm wafer)
MTBA	> 6 hours
MTBF	> 1000 hours
Options	Real-time Statistical Process Control SECS/GEM Compatible
User Interface	Windows 7 platform with GUI Full machine diagnostics capability

INSPECTION	DETAILS
2D OTF™	Scratch Damage FM defects Edge chip out Corner chip out Saw offset cut
3D OTF™	Coplanarity Bump Height

SPECIFICATIONS	DETAILS
FACILITIES	
AC Power Supply	230 VAC, 30 A, 50/60 Hz, one phase
Air Supply	0.49 MPa – 0.59 MPa, 300 l/min
Vacuum	-60 kPa to -80 kPa, ≥ 20 l/min
Environment	15° - 30°C 50% - 70% relative humidity
Dimension	2280 x 1780 x 2004 mm 1835 x 1360 x 2004 mm (without port)
Weight	2000 kg

Layout

